IPC ASSOCIATION ELECTRONIC		Material Composition Declaration  © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.		nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials an	ials and Mfg Information				
upplie	r Information														
Company name*			Company un	Company unique ID			Unique ID Authority				Res	Response Date*			
nsemi										2023	2023-06-08				
Contact N	Name	Title - Contact			I	Phone - Contact*				Ema	Email - Contact*				
Product-l	Env-Stewards	Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*	Title - Representative			I	Phone - Representative*				Ema	Email - Representative*				
Product-	Env-Stewards	Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Version Manufacturing Site		Site	Weight*	UOM	Unit Type		
		NCP302	CP302055MNTWG INT Driver and MOS		OSFET		2023-06-08		MY5			73.67428	mg	Each	
Ianufa	ecturing Proccess Inform													·	
			, and the second		-STD-020 MSL	Rating			ure Max Time at Peak Temperat		erature Number	er of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Alloy			1			260		C	30	Se	econds 3				
omments															
	naximum time at peak tempera														
or more	information regarding materi	al composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not independently verified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.34295	mg	Supplier	Zinc (Zn)	7440-66-6		0.0076	mg
			Supplier	Iron (Fe)	7439-89-6		0.1522	mg
			Supplier	Copper (Cu)	7440-50-8		6.178	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0051	mg
Die	0.317142	mg	Supplier	Silicon (Si)	7440-21-3		0.3171	mg
Die Attach Solder	2.17762	mg	Supplier	Silver (Ag)	7440-22-4		0.0544	mg
			A	Lead (Pb)	7439-92-1	7a	2.0143	mg
			Supplier	Tin (Sn)	7440-31-5		0.1089	mg
Epoxy	0.1291	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0103	mg
			Supplier	Bismaleimide	13676-54-5		0.0348	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		0.0116	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0013	mg
			Supplier	PTFE	9002-84-0		0.071	mg
Lead Frame	31.0723	mg	Supplier	Silver (Ag)	7440-22-4		1.5538	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0373	mg
			Supplier	Iron (Fe)	7439-89-6		0.7458	mg
			Supplier	Copper (Cu)	7440-50-8		28.7106	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0249	mg
Mold Compound-Black	31.2746	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.0328	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1564	mg
			Supplier	Silica (SiO2)	14464-46-1		27.5216	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.5637	mg
Plating	2.10085	mg	Supplier	Tin (Sn)	7440-31-5		2.1009	mg
Wire Bond - Cu	0.259717	mg	Supplier	Palladium (Pd)	7440-05-3		0.0047	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.2548	mg